



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP Compaq 8000 Elite Small Form Factor Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)	-	0
Capacitors / condensers (Containing PCB/PCT)	-	0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	power supply	up to 13
External electrical cables and cords	-	0
Gas Discharge Lamps	-	0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	fans	3
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos	-	0

Components, parts and materials containing refractory ceramic fibers	-	0
Components, parts and materials containing radioactive substances	-	0

1.3 Markings for plastic parts greater than 25 grams

Plastic Part Name	Plastic Part Description	Weight (grams)	ISO 11469:2000 Plastic Part Mark	Optional: Photo
Main Bezel	Main bezel of desktop product	89g	>ABS<	
Fan Duct	System fan holder of desktop product	58.7g	>PC+ABS FR(40)<	
Fan Holder	Fan holder of desktop product	44.9	>PC+ABS FR(40)<	
System Fan Frame_ADDA	System Fan Frame of desktop product	45g	>PBT-GF30 FR(17)<	
System Fan Frame_DELTA	System Fan Frame of desktop product	45g	>PBT-GF30-FR(17)<	
Chassis Stand	Chassis Stand of desktop product	78.0g	>ABS<	
DC Fan Frame_ADDA	DC Fan Frame of desktop or tower product	40g	>PBT-GF30 FR(17)<	
DC Fan Frame_DELTA	DC Fan Frame of desktop or tower product	40g	>PBT-GF30-FR(17)<	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Philips Screw Driver	100mm
Description #2 Diagonal cutting pliers	130mm
Description #3 Long nose pliers	NA
Description #4 Unsolder tool	NA
Description #5 Solder machine	230mm

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel (see figure 1-2)
2. Remove the front bezel (see figure 3-4)
3. Remove Fan duct and heatsink (see figure 5-11)
4. Remove CPU (see figure 12-13)
5. Remove Memory Module (see figure 14-15)
6. Disconnect all internal cable from PCA (see figure 16)
7. Remove ODD and rotate ODD cage (see figure 17-18)
8. Remove 1st HDD (see figure 19-20)
9. Remove PCA (see figure 22-23)
10. Remove Battery (see figure 24-25)

11. Release PSU case (see figure26-28)
12. Remove PSU PCA and Fan (see figure29-32)
13. Remove electrical capacitors from PCA (see figure33)
- 14.
- 15.
- 16.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1: Pull Lock



Figure 2: Rise access panck Press front panel clip



Figure 3: Pull 3 retaining clips on the bezel top side



Figure 4: Release the front bezel. Rotate the bezel outward to remove it from the chassis



Figure 5: Remove all cable from cable clamp



Figure 6: Release Fan duct



Figure 7: Press 2 clip to Remove Fan holder from front chassis,

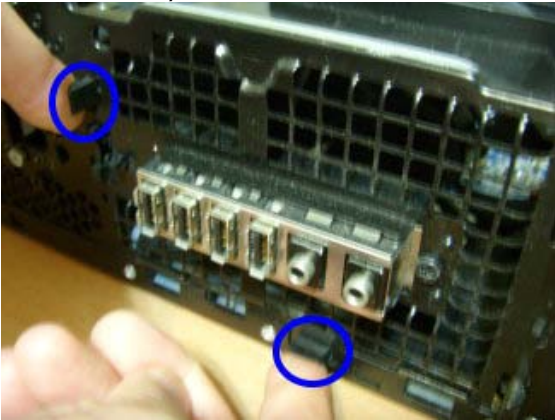


Figure 8: Disconnect Fan connector from PCA header

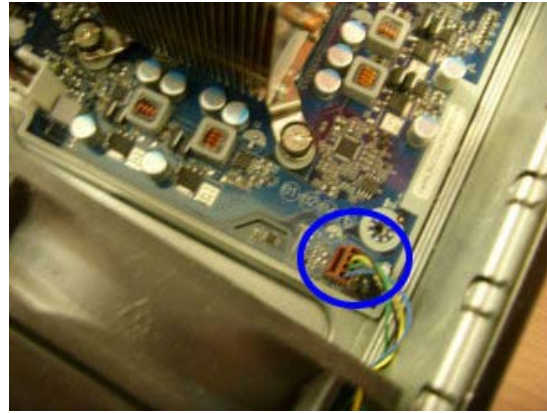


Figure 9 : Remove fan and fan holder from chassis



Figure 10 : Wresting screw with screw driver release 4 qyt's screw



Figure 11: Remove Heat sink from PCA



Figure 12: Press CPU chassis lock

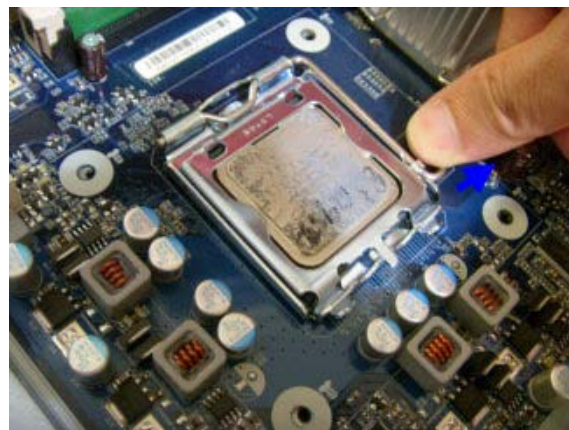


Figure 13: Remove CPU



Figure 14: Unlock Memory DIMM lock

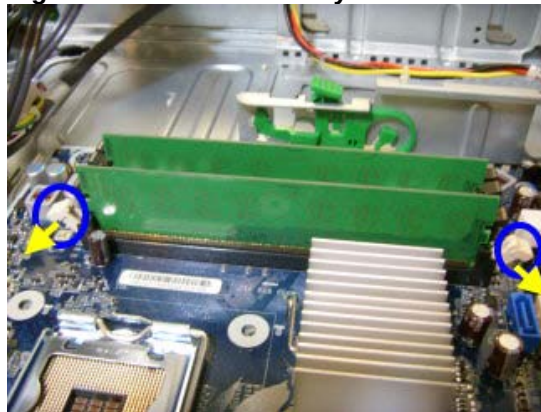


Figure 15 :Remove Memory DIMM from PCA



Figure 16: Remove all internal cable from PCA



Figure 17: Release ODD from ODD cage
Press ODD latch and push ODD toward PSU.



Figure 18: Rotage ODD cable to vertical



Figure 19: Rotate PSU to Vertical



Figure 20: Release HDD Press HDD latch and push HDD toward Front side.



Figure21: Remove PSU from Chassis



Figure 22: Release PCA 8 screws by wresting screw with screw driver



Figure 23: Remove PCA from Chassis



Figure 24: Press Battery holder and Pull battery

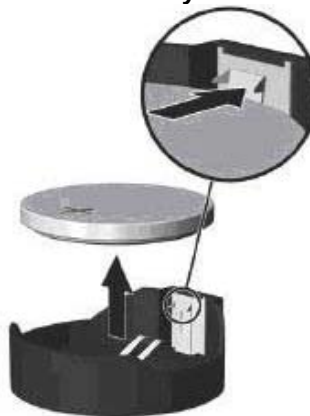


Figure 25: Remove Battery



Figure 26: Cut the plastic cable tie from PSU case



Figure 27: Release PSU 7 screws by wrest screw driver

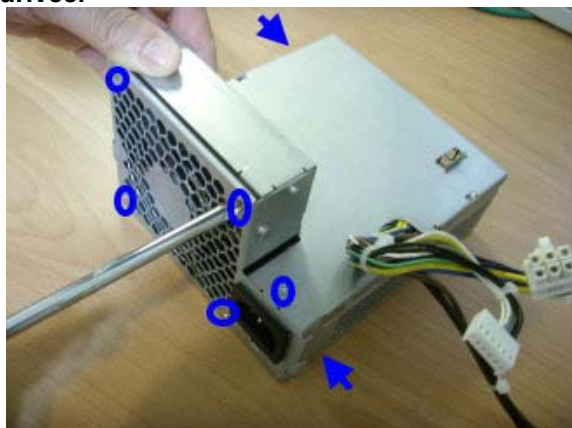


Figure 28: Remove PSU the top of case



Figure 29: Cut PSU PCA wire (2) and disconnect Fan connector



Figure 30: Remove PSU PCS 5 screws

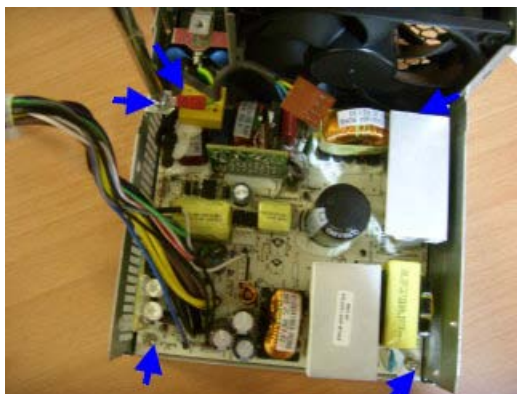


Figure 31 : : Remove PSU FAN



Figure 32: Remove PSU PCA from case



Figure 33 Remove electrical capacitors

